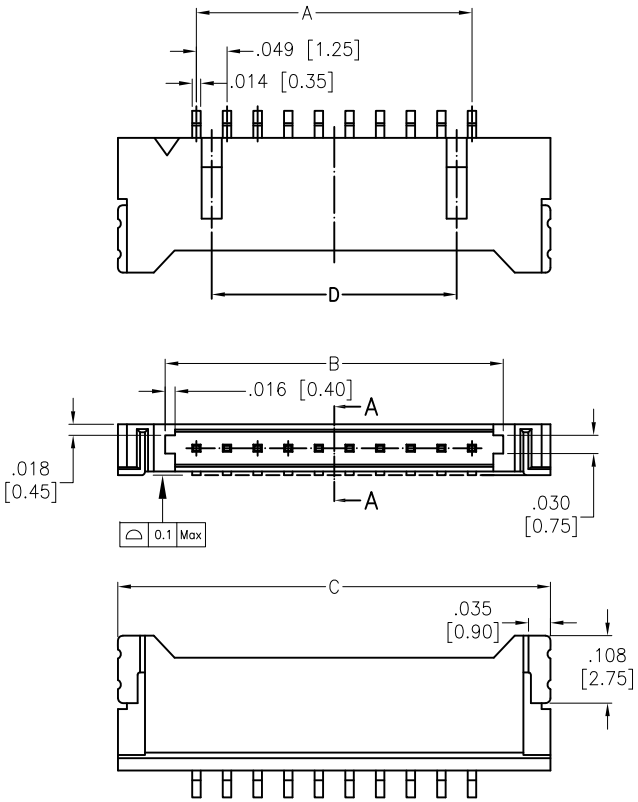
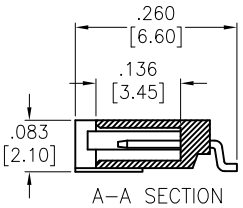
Rev	AWO #	Description	Date	Appr
-		RELEASED	9/8/11	

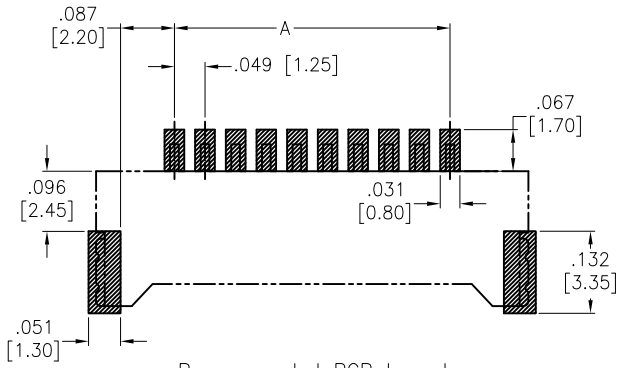
APPROVED: _____

DATE: _____ TITLE: _____

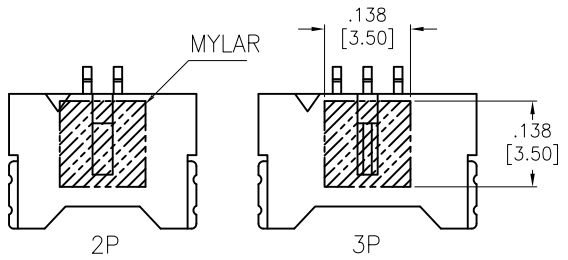




A–A SECTION



Recommended PCB Layout



PACKAGED ON TAPE & REEL
Positions: 02 thru 30
A = .049 [1.25] x No. of Spaces
B = .049 [1.25] x No. of Spaces + .100 [2.55]
C = .049 [1.25] x No. of Spaces + .252 [6.40]
D = (4~19 Positions)= .049 [1.25] x No. of Spaces −.049 [1.25]
(20~30 Positions)= .886 [22.50]

SPECIFICATIONS:
Material:
Insulator: Hi−temp thermoplastic, rated UL 94V−0
Insulator color: Natural
Contacts: Copper alloy
Solder Nail: Brass, Tin plated
Plating:
Tin over Copper underplate overall
Electrical:
Current rating: 1.0A AC,DC
Contact resistance: 20 mohms max. initial
Insulation resistance: 100 Mohms min.
Dielectric withstanding voltage: 250 VAC for 1 minute
Temperature Rating:
Operating temperature: −25°C to +85°C
Environmental:
Lead free, RoHS compliant RoHS COMPLIANT

UNLESS OTHERWISE SPECIFIED
ALL DIMENSIONS ARE INCHES [MM]
TOLERANCES: EXCEPT AS NOTED

INCHES		HOLES	
.X	± .10	Ø.X	±.10
.XX	± .020	Ø.XX	±.015
.XXX	± .015	Ø.XXX	±.010

APPROVALS		DATE
DRAWN	AY	9/8/11
CHECKED	OC	9/8/11
APPROVED		

ADAM TECH
909 Rahway Avenue, Union, NJ 07083
Phone: 908-687-5000 Fax: 908-687-5710

TITLE: .049 [1.25] WAFER, SMT, RIGHT ANGLE TIN PLATED

SIZE	PART NO.	REV.
X	125SH-H-XX-TR-SMT-T/R	-

REF: S00124T | SCALE: NTS | SHEET 1 OF 1